

Abstract

The present application relates to a vacuum suction heater, comprising: a heating plate, wherein the heating plate comprises a generally disc-shaped main body, the main body has an upper surface for bearing a wafer, and further comprises: a plurality of grooves extending downwards from the upper surface, wherein at least a portion of the plurality of grooves are fluid connected to each other; one or more passing holes , which are fluid connected to at least one of the plurality of grooves; and a plurality of protrusions situated on the upper surface, which are used to support the wafer. The heater can create uniform point contact between the bearing surface and the wafer placed thereon, thus effectively sucking the wafer during operation, preventing wafer movement on the bearing surface of the heater, as well as ensuring that the entire wafer is uniformly heated, thereby improving product quality of the wafer.

(FIG. 1)